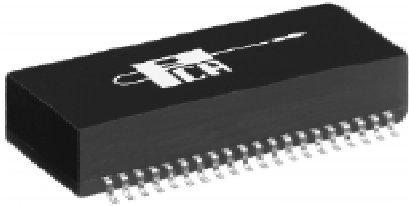


10/100 Base-X Module for Level One LXT 974 Multi-Port Applications

EPF8082S



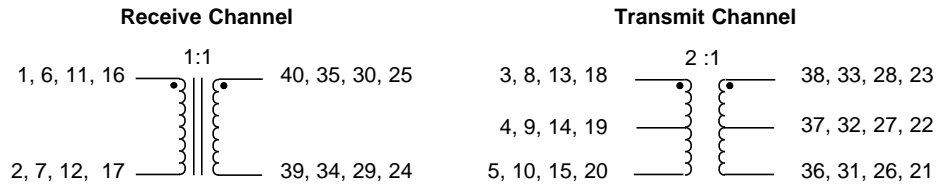
- Robust design allows for toughest soldering processes •
- Guaranteed to operate with 8 mA DC bias at 70°C •
- Complies with or exceeds IEEE 802.3, 10 BT/100 BX Standards •

Electrical Parameters @ 25° C

OCL @ 70°C	Insertion Loss (dB Max.)						Return Loss (dB Min.)						Crosstalk (dB Min.)
	0.1-80 MHz		100 MHz		150 MHz		1-30 MHz		60 MHz		100 MHz		
100 KHz, 0.1 Vrms 8 mA DC Bias													0.1-100 MHz
Media Side	Xmit	Rcv	Xmit	Rcv	Xmit	Rcv	Xmit	Rcv	Xmit	Rcv	Xmit	Rcv	
350µH	-1	-1	-1	-1	-3	-3	-18	-18	-12	-12	-10	-10	-35

• Isolation : 1500 Vrms • Impedance : 100 Ω • Rise Time : 3.0 nS Max.

Schematic



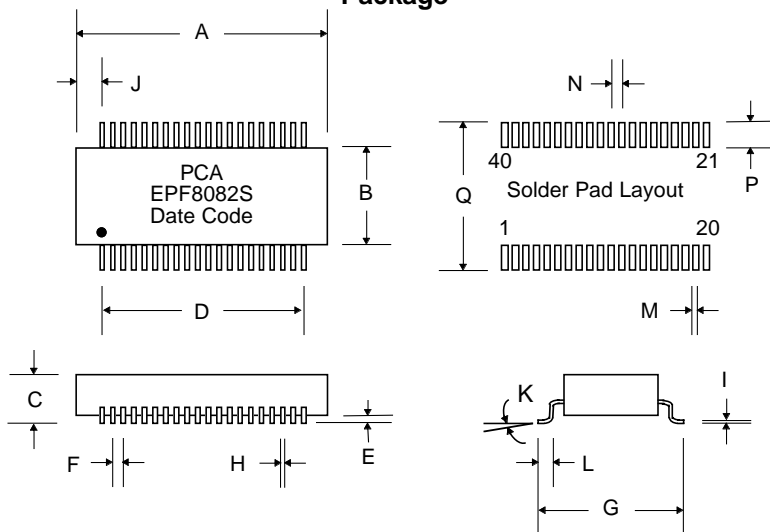
Chip
Side

Media
Side

Chip
Side

Media
Side

Package



Dimensions

Dim.	(Inches)			(Millimeters)		
	Min.	Max.	Nom.	Min.	Max.	Nom.
A	1.110	1.130		28.19	28.70	
B	.470	.490		11.94	12.45	
C	.235	.255		5.97	6.48	
D	.950	Typ.		24.13	Typ.	
E	.008	.012		.203	.305	
F	.050	Typ.		1.27	Typ.	
G	.580	.600		14.73	15.24	
H	.016	.022		.406	.559	
I	.008	.012		.203	.305	
J	.085	Typ.		2.16	Typ.	
K	0°	8°		0°	8°	
L	.025	.045		.635	1.14	
M			.030			.762
N			.050			1.27
P			.090			2.29
Q			.670			17.02